



Material Content Data Sheet



Sales Product Name		BSZ036NE2LS		Issued		19. July 2018		
MA#		MA001002422						
Package		PG-TSDSON-8-25		Weight*		35.42 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.285	0.80	0.80	8033	8033
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		69	
	non noble metal	zinc	7440-66-6	0.010	0.03		278	
	non noble metal	iron	7439-89-6	0.197	0.56		5555	
wire	non noble metal	copper	7440-50-8	7.988	22.55	23.15	225549	231451
	noble metal	gold	7440-57-5	0.029	0.08	0.08	830	830
encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1077	
	plastics	epoxy resin	-	1.965	5.55		55473	
	inorganic material	silicondioxide	60676-86-0	17.072	48.19	53.85	482025	538575
leadfinish	non noble metal	tin	7440-31-5	0.395	1.12	1.12	11160	11160
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	574	574
solder	noble metal	silver	7440-22-4	0.012	0.03		327	
	non noble metal	tin	7440-31-5	0.009	0.03		262	
	non noble metal	lead	7439-92-1	0.442	1.25	1.31	12490	13079
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33	
	non noble metal	zinc	7440-66-6	0.005	0.01		133	
	non noble metal	iron	7439-89-6	0.094	0.27		2653	
	non noble metal	copper	7440-50-8	3.816	10.77	11.05	107741	110560
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
	non noble metal	iron	7439-89-6	0.073	0.21		2058	
	non noble metal	copper	7440-50-8	2.959	8.36	8.58	83551	85738
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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